

**EAST Search History****EAST Search History (Prior Art)**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L14	191	257/782.ccls. laser	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/03/10 09:27
L15	32	257/782.ccls. laser near3 (dicing or dice or cut\$4 or scrib\$3 or singulat\$3 or divid\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	AND	ON	2011/03/10 09:27

**EAST Search History (Interference)**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L16	0	438,113,118,460-465. ccls. (wafer (adhesive or tape) (cure or cured or curing) laser (cut\$4 or singulat\$3 or dice or diced or dicing) die bond \$3).clm.	US- PGPUB; USPAT; UPAD	AND	ON	2011/03/10 09:39
L17	0	438,113,118,460-465. ccls. (wafer (adhesive or tape) (cure or cured or curing) laser (cut\$4 or singulat\$3 or dice or diced or dicing) bond\$3). clm.	US- PGPUB; USPAT; UPAD	AND	ON	2011/03/10 09:39
L18	0	438,113,118,460-465. ccls. (wafer (adhesive or tape) (cure or cured or curing) laser (cut\$4 or singulat\$3 or dice or diced or dicing)).clm.	US- PGPUB; USPAT; UPAD	AND	ON	2011/03/10 09:39

L19	14	257/782,E21.599, E21.598,E21.6.ccds. (wafer (adhesive or tape) (cure or cured or curing) laser (cut\$4 or singulat\$3 or dice or diced or dicing)).clm.	US- PGPUB; USPAT; UPAD	AND	ON	2011/03/10 09:40
L20	77	(wafer (adhesive or tape) (cure or cured or curing) laser (cut\$4 or singulat\$3 or dice or diced or dicing)).clm.	US- PGPUB; USPAT; UPAD	AND	ON	2011/03/10 09:42
L21	63	20 not 19	US- PGPUB; USPAT; UPAD	AND	ON	2011/03/10 09:42

3/10/2011 9:52:24 AM

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